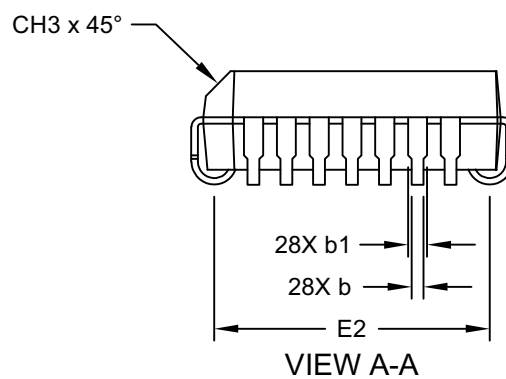
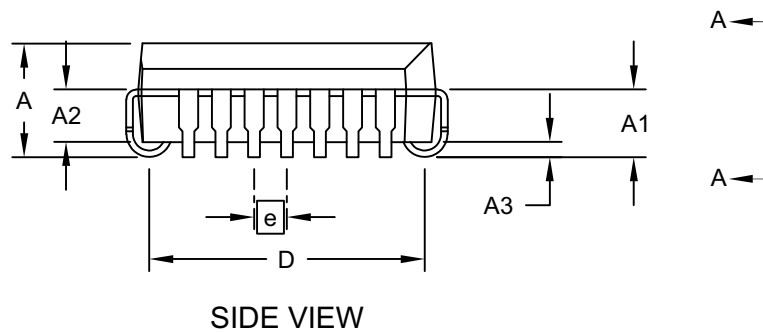
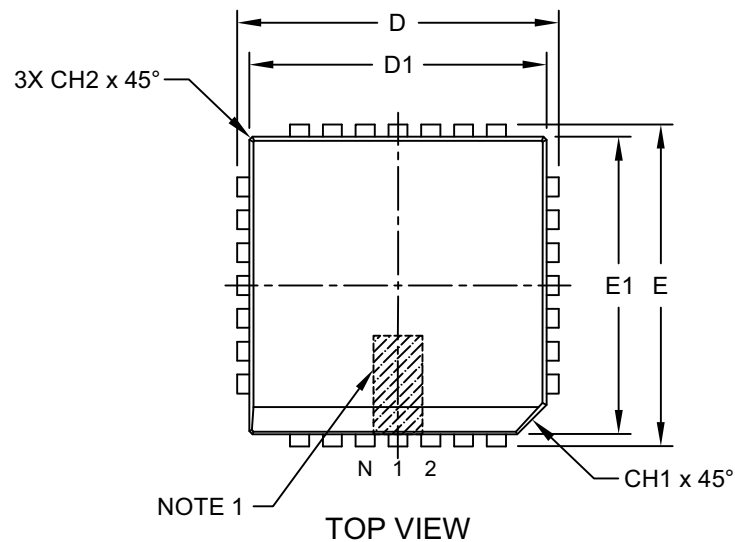


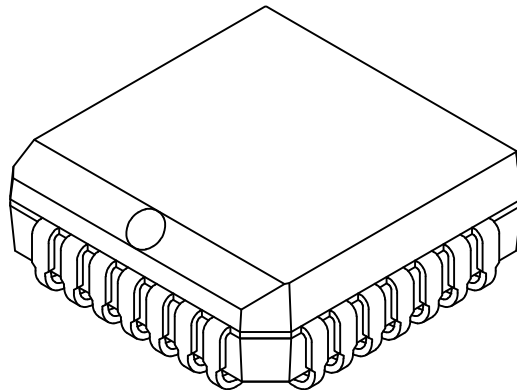
## 28-Lead Plastic Leaded Chip Carrier (L) - Square [PLCC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## 28-Lead Plastic Leaded Chip Carrier (L) - Square [PLCC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	N	28			28		
Pitch	e	.050			1.27		
Overall Height	A	.165	.172	.180	4.19	4.37	4.57
Contact Height	A1	.090	.105	.120	2.29	2.67	3.05
Molded Package to Contact	A2	.062	-	.083	1.57	-	2.11
Standoff §	A3	.020	-	-	0.51	-	-
Corner Chamfer	CH1	.042	-	.048	1.07	-	1.22
Chamfers	CH2	-	-	.020	-	-	0.51
Side Chamfer	CH3	.042	-	.056	1.07	-	1.42
Overall Width	E	.485	.490	.495	12.32	12.45	12.57
Overall Length	D	.485	.490	.495	12.32	12.45	12.57
Molded Package Width	E1	.450	.453	.456	11.43	11.51	11.58
Molded Package Length	D1	.450	.453	.456	11.43	11.51	11.58
Footprint Width	E2	.382	.410	.438	9.70	10.41	11.13
Footprint Length	D2	.382	.410	.438	9.70	10.41	11.13
Lead Thickness	c	.0075	-	.0125	0.19	-	0.32
Upper Lead Width	b1	.025	-	.032	0.64	-	0.81
Lower Lead Width	b	.013	-	.021	0.33	-	0.53

**Notes:**

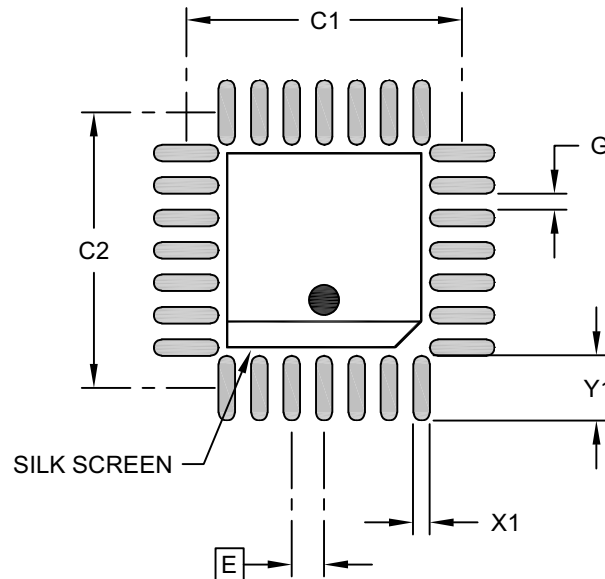
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
- Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-026-L Rev C Sheet 2 of 2

## 28-Lead Plastic Leaded Chip Carrier (L) - Square [PLCC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

Units		INCHES			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Contact Pitch	E	.050 BSC			1.27 BSC		
Contact Pad Spacing	C1		.425			10.80	
Contact Pad Spacing	C2		.425			10.80	
Contact Pad Width (X28)	X1			.026			0.66
Contact Pad Length (X28)	Y1			.100			2.54
Contact Pad to Center Pad (X24)	G	.008			0.20		

#### Notes:

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2026-L Rev C